

Nitrided Metallic Bipolar Plates

M.P. Brady (project lead)

P. F. Tortorelli

Oak Ridge National Laboratory

Oak Ridge, TN 37831-6115

contact: bradymp@ornl.gov

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Effort Devoted to Scale Up and Demonstration of Thin Stamped Metallic Bipolar Plates

Timeline

- Start- May 1, 2007
- Finish- May 1, 2010
- New Project

Budget

- Total project funding
 - \$4530 K (+ \$400 K Match)
- Funding for FY2007
 - \$1200 K

Barriers

- A. Durability
- B. Cost

Targets (2010)

- resistivity < 10 mohm-cm²
- corrosion < 1 x10⁻⁶ A/cm²
- cost < \$5/kW

Team Members

- ORNL (Lead)
- Allegheny Ludlum
- Arizona State University
- GenCell Corp
- LANL
- NREL

Objective: Surface Treatment to Protect Stamped Metallic Bipolar Plates

Overall Goal: ***Demonstrate potential for metallic bipolar plates to meet 5000 h automotive durability goal at cost < \$5/kW***

Year 1 Goal:

No significant warping or embrittlement of the stamped plates by the nitriding-amenability of approach established for thin stamped foils

Year 2 Goal:

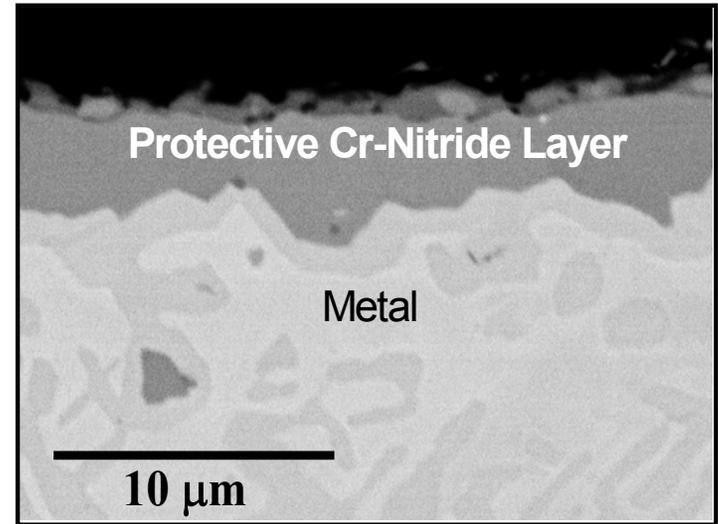
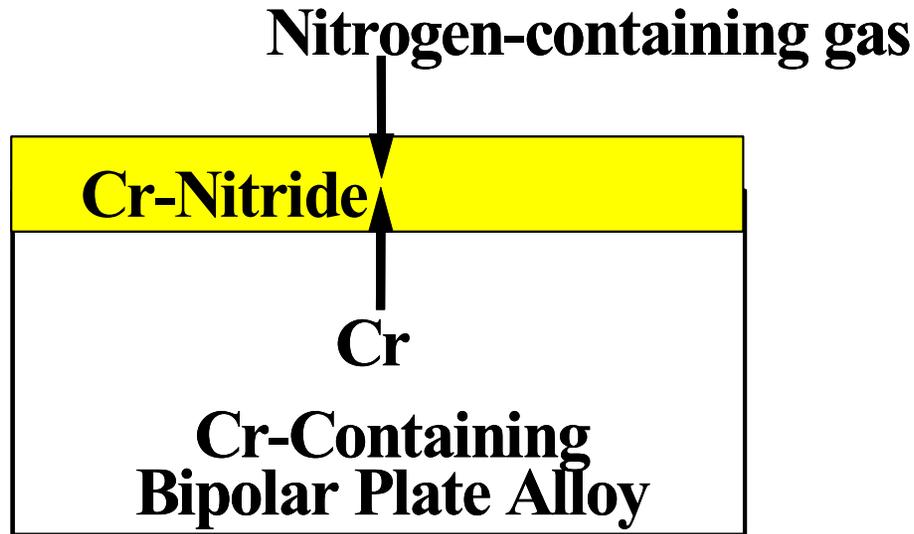
Single-cell fuel cell test performance for ~25 cm² stamped and nitrided metallic bipolar plates equivalent to that of graphite (~1000 h, cyclic)

Year 3 Goal:

10 cell stack test of 250 cm² stamped and nitrided metallic bipolar plates under automotive drive-cycle conditions (~2000 h)

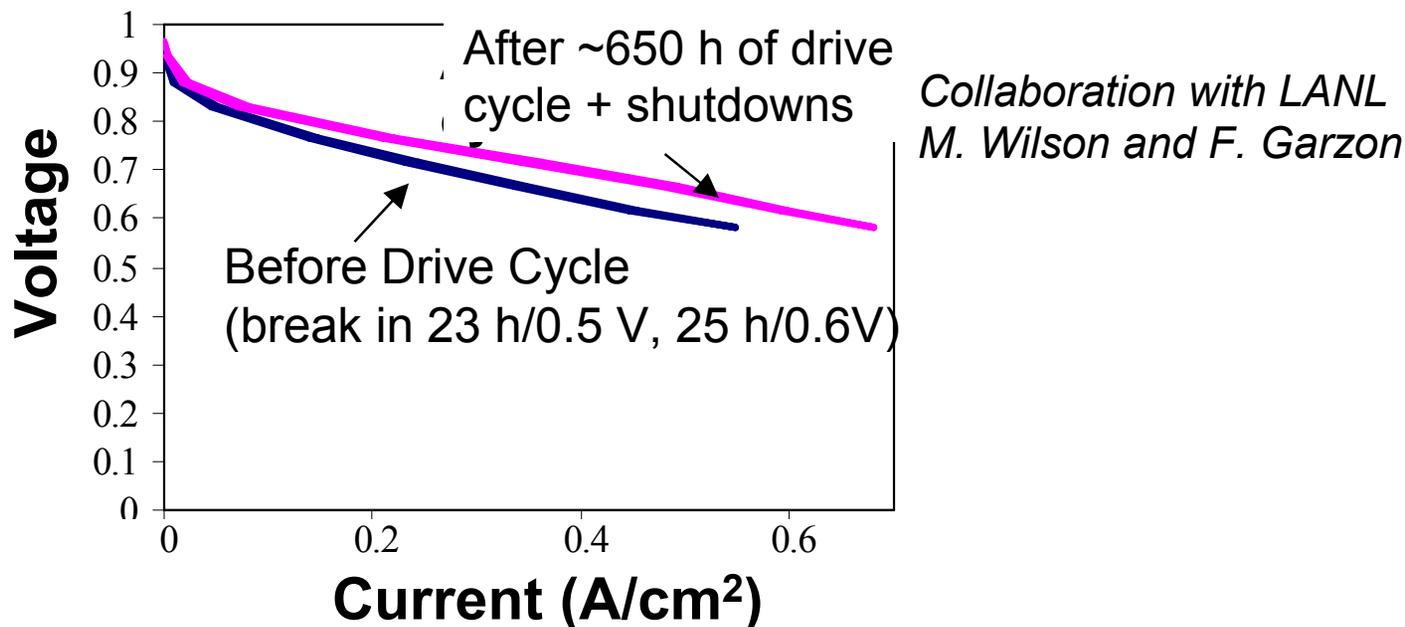
Potential to manufacture stamped and nitrided metallic bipolar plates at < \$5/kW demonstrated

Approach: Thermally Grown Cr-Nitride for Protection



- **Surface conversion, not a deposited coating: High temperature favors reaction of all exposed metal surfaces**
 - No pin-hole defects (other issues to overcome)
 - Amenable to complex geometries (flow field grooves)
- **Stamp then nitride: Industrially established and cheap**

Good Single-Cell Drive-Cycle Durability Test Results for Model Nitrided Ni-50Cr Plates



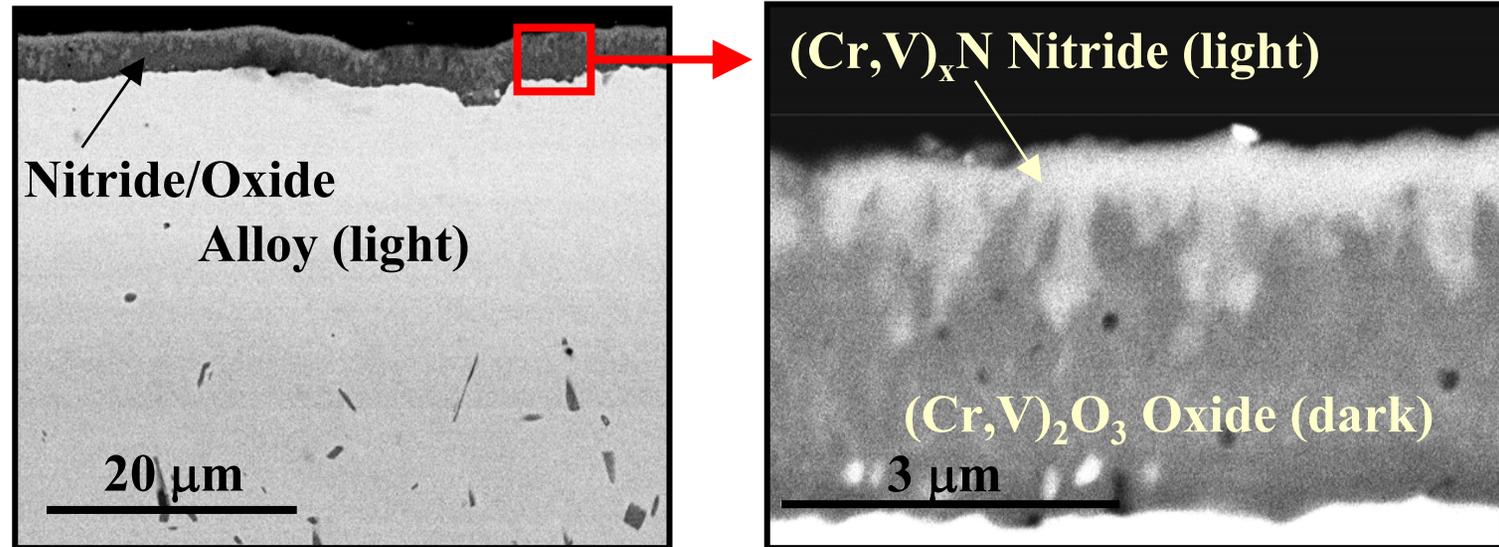
- **1160 h of drive-cycle testing** (after initial 500 h/0.7V/80°C test screening)
 - 0.94V/1 min; 0.60V/30 min; 0.70V/20 min; 0.50V/20 min
 - additional 24 full shutdowns superimposed
- No performance degradation/No attack of the Cr-nitride
 - trace level (2×10^{-6} g/cm²) of Ni detected in MEA, suspect local CrNiN spots

Need Fe-Base Alloys to Meet \$5/kW Bipolar Plate Cost Goals

- **Dense Cr-nitride surface formation demonstrated on a model Fe-base alloy, Fe-27Cr-6V wt.%**
 - pre-oxidation key to protective surface nitride formation
 - V segregation into Cr-oxide makes it more readily nitrided
- **Alloy Challenges**
 - Lower Cr and V levels to reduce alloy cost
 - Co-optimize preoxidation/nitridation to segregate Cr, V to surface
 - Down select to ferritic (cheaper) or austenitic (more formable) alloy base

Dense, Continuous Nitride Surface Obtained

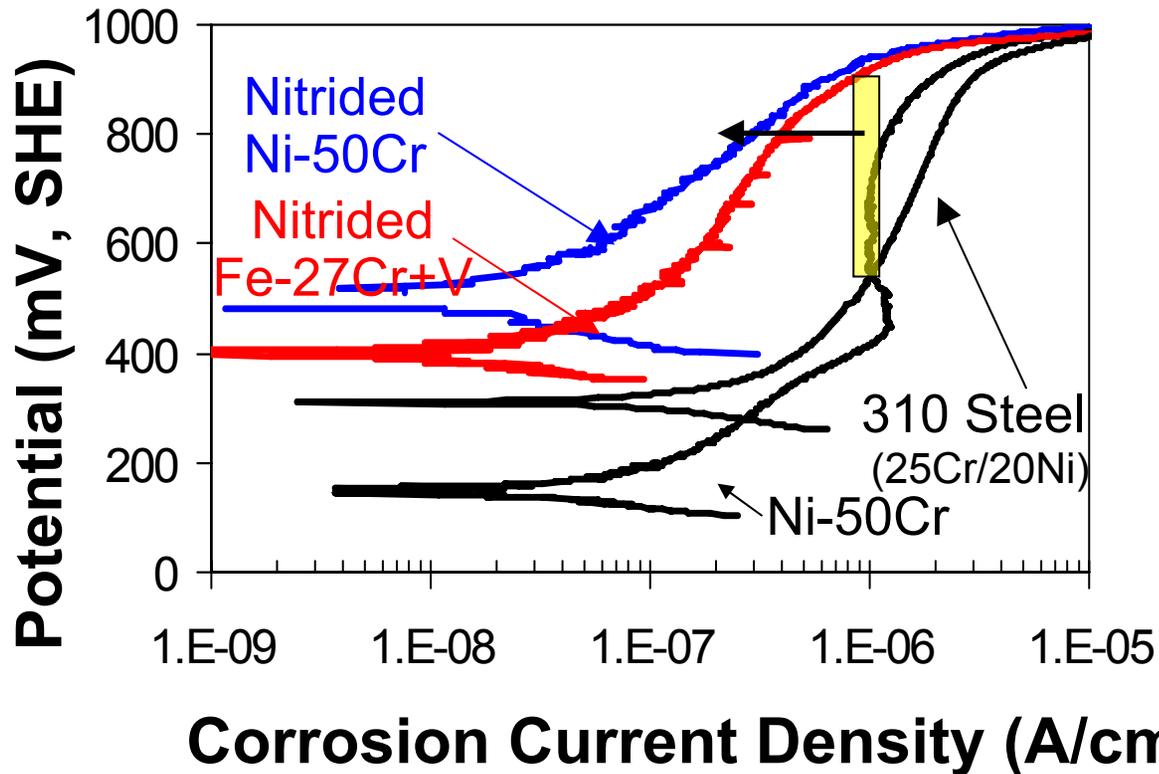
SEM Cross-Sections of Preoxidized and Nitrided Fe-27Cr-6V



- Low contact/through-thickness electrical resistance
- Low corrosion current densities under simulated anodic and cathodic conditions

Vanadium Additions to Fe-27Cr Result in Protective Cr-Nitride Surface

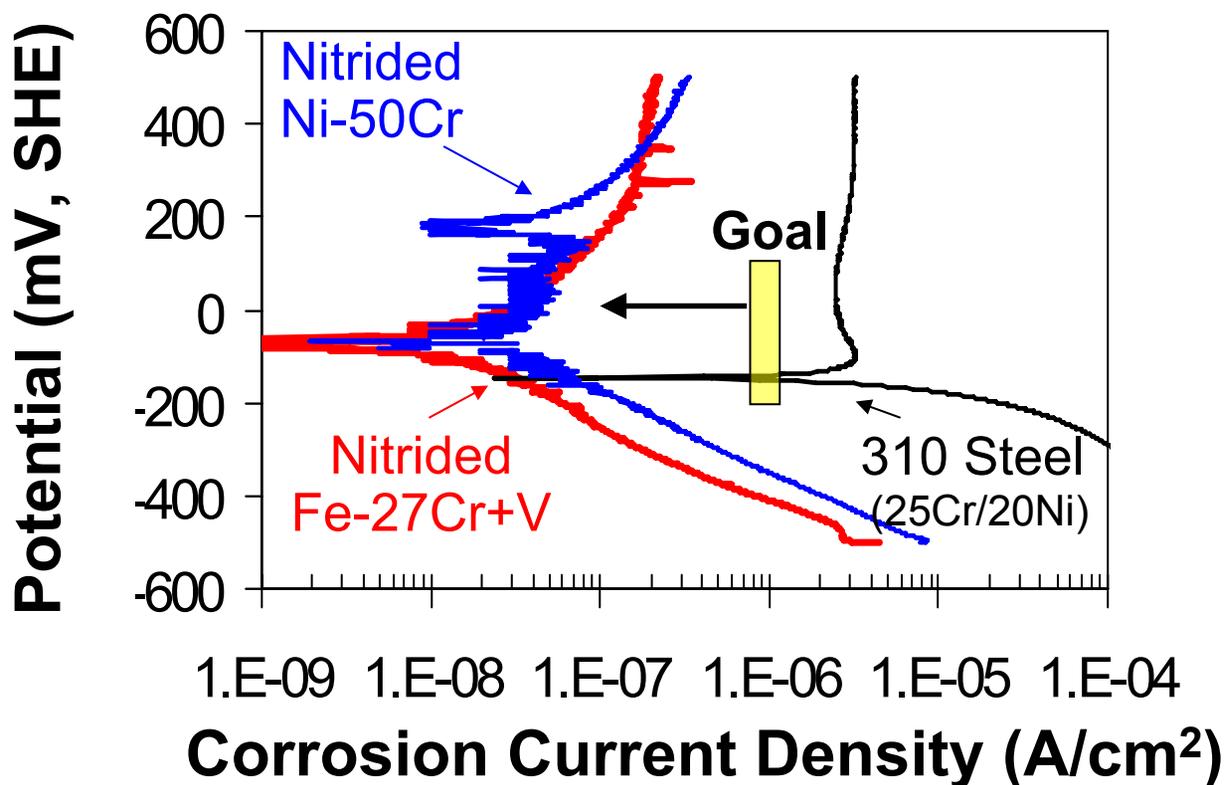
Polarization in Aerated pH 3 Sulfuric Acid at 80°C



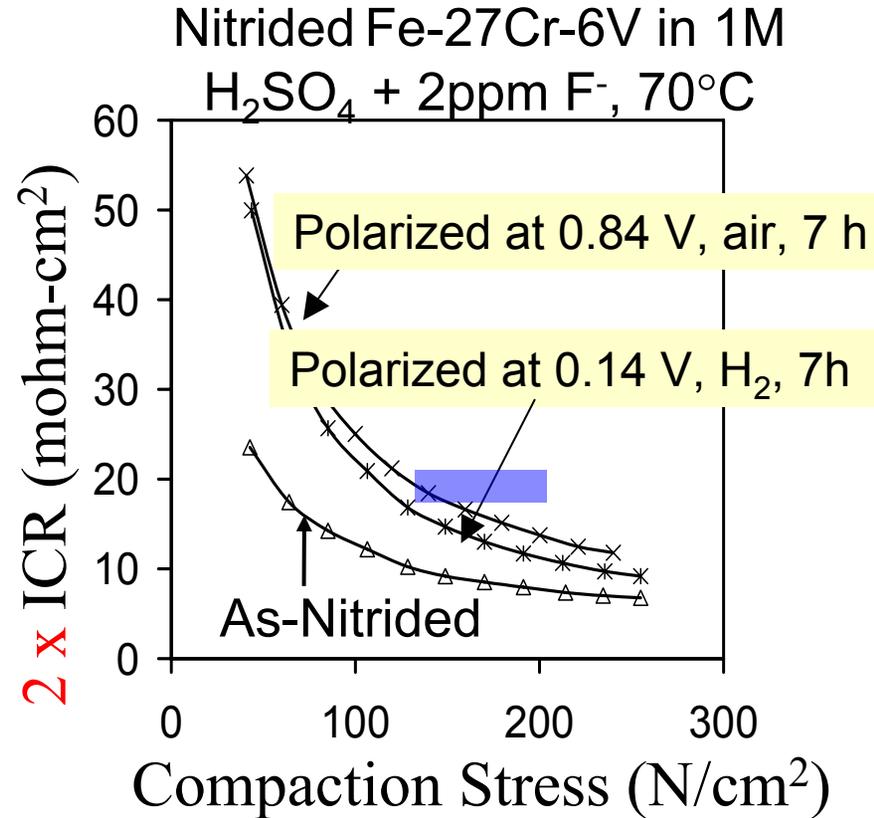
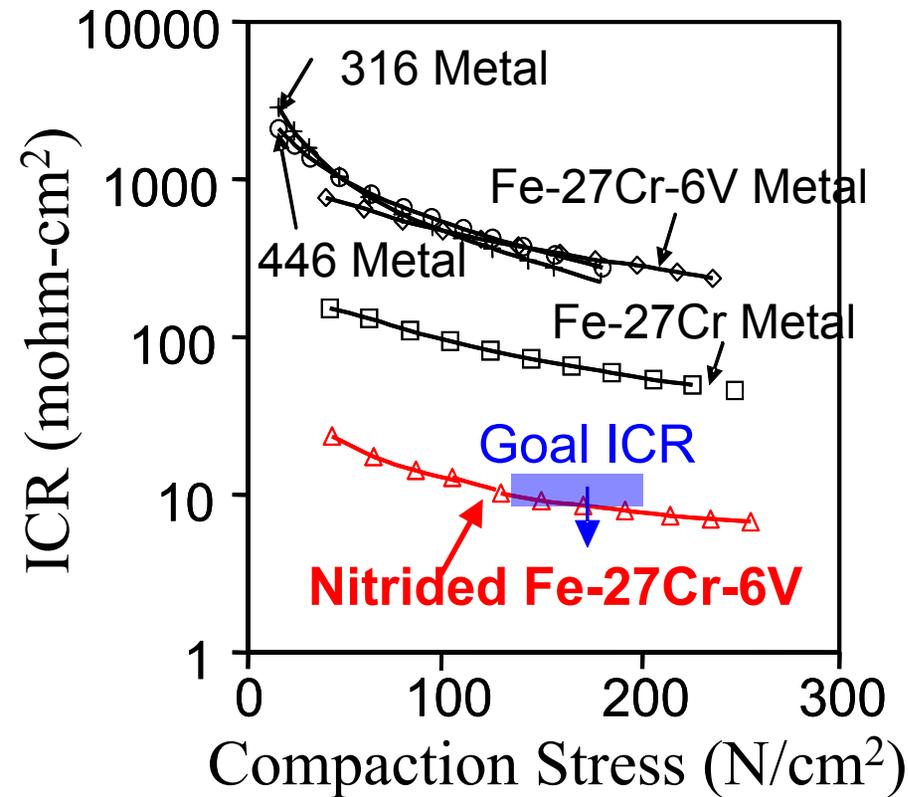
Corrosion resistance comparable to nitrided Ni-50Cr observed for nitrided Fe-27Cr-2V and Fe-27Cr-6V (850-900°C, < 24 h, N₂-4H₂)

Good Corrosion Resistance Also Observed Under Simulated Anode Conditions

Polarization in Ar-4H₂ Purged pH 3 Sulfuric Acid at 80°C



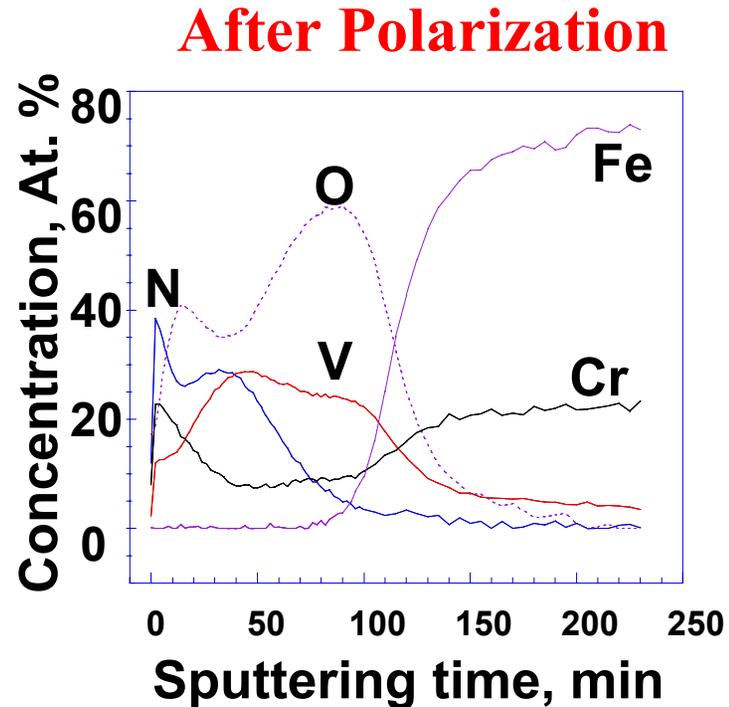
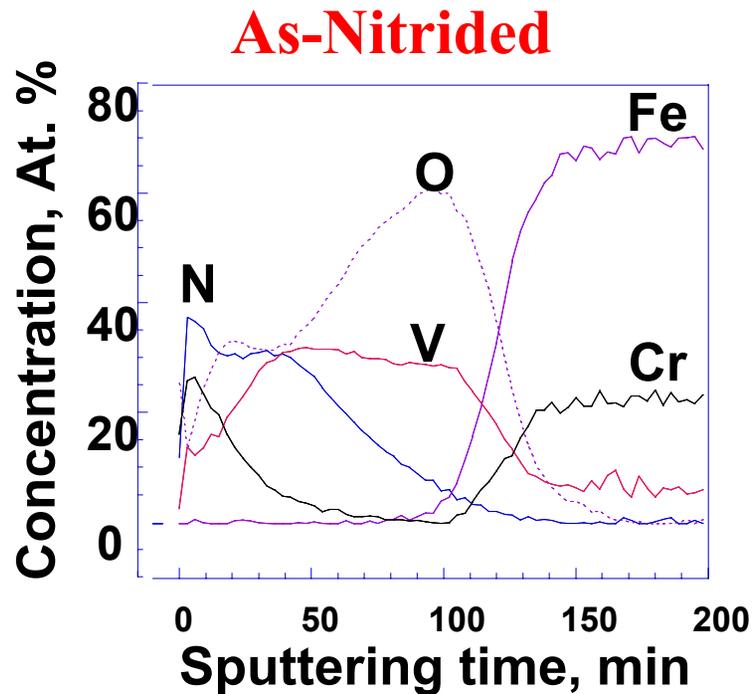
Nitrided Fe-27Cr-6V Meets and Maintains Contact Resistance Goal



- Nitridation significantly reduces interfacial contact resistance (ICR)
- Slight increase in ICR on polarization-still meets goal
- Untreated stainless steels don't meet ICR goals

Little Effect of Polarization on Surface Chemistry of Nitrided Fe-27Cr-6V

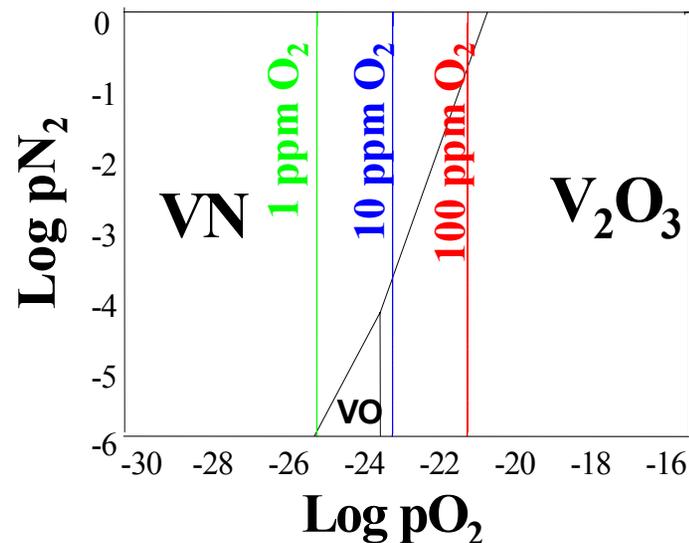
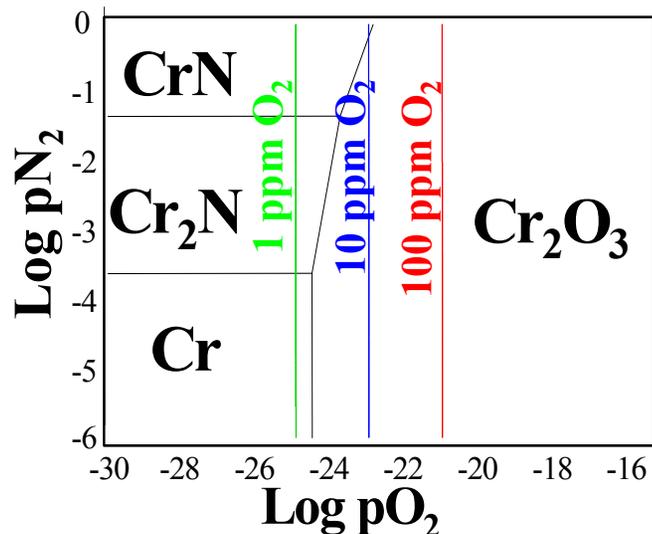
Auger Electron Spectroscopy of Nitrided Fe-27Cr-6V



- Polarized 7 h at 0.84 V SHE in 1M H₂SO₄ + 2 ppm F⁻ air purged at 70 °C (similar results under H₂-purged anodic conditions)
- No Fe detected in nitrided surface

V Additions Destabilize Oxide Relative to Nitride Compared to Cr

900°C Predominance Diagrams



- Order of magnitude greater O₂ impurity stability for VN relative to CrN at 900°C in N₂-4H₂ (100 vs 10 ppm O₂)
- V works because Cr₂O₃-V₂O₃; Cr₂N-V₂N; CrN-VN all mutually soluble
- V₂O₃ and Cr-doped V₂O₃ also conductive – combined with intermixed morphology and N₂-doping yields good ICR values

Teaming and Primary Responsibilities

- **Oak Ridge National Lab:**
Alloy design, nitridation optimization, characterization
- **National Renewable Energy Lab:**
Corrosion/contact resistance evaluation
- **Allegheny Ludlum:**
Alloy foil manufacture
- **GenCell Corp:**
Design and stamp bipolar plate flow field features
- **Arizona State University:**
Single-cell testing (assisted by Gencell, ORNL)
- **Los Alamos National Lab:**
Stack testing and performance assessment, characterization

Stamped Fe-Cr-V Alloys Can Meet \$5/kW Transportation Cost Goals

GenCell Corp Cost Estimates for Stamped Bipolar Plates (Nitriding Costs Not Included)

Foil Thick. (in)	Density kg/kW	Bipolar Plate Cost (\$/kW)		
		<u>\$3/lb Alloy</u>	<u>\$5/lb Alloy</u>	<u>\$7/lb Alloy</u>
0.002	0.26	\$2.31	\$3.47	\$4.58
0.004	0.38	\$3.15	\$4.26	\$6.57
0.008	0.64	\$4.86	\$7.69	\$10.51

High Cr ferritic alloys \$3-7/lb: **viable nitriding costs**

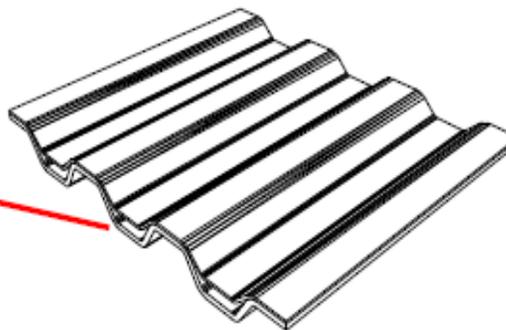
- E-BRITE® (Fe-26Cr-1Mo wt.%): \$5-7/lb commercial price for foil
- Alloy 444 (Fe-18Cr-2Mo wt.%): \$3-5/lb commercial price for foil
- Above alloys comparable to Fe-Cr-V alloys as Mo and V costs similar

Assumptions: 360 cm² active area plate (494 cm² total area), 2 mil secondary foil for cooling (nested stacking), parallel flow field 0.025" depth, 2010 MEA target power density

GenCell Corp Stamped Bipolar Plate Approach

Internal Chamber (patented)

- "Heat exchanger in each cell"
- Thin wall, high surface area
- From same tooling using nested sheet metal



Above shown for molten carbonate fuel cell bipolar plates, approach currently being extended to PEM and SOFC